



SOT1225

plastic extremely thin small outline package; no leads; 8 terminals; body 1.6 x 1.2 x 0.4 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	DFN1612-8
Package type industry code	DFN1612-8
Package style descriptive code	XSON (extremely thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	24-7-2012

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.55	-	1.6	1.65	mm
E	package width	1.15	-	1.2	1.25	mm
A	seated height	0.34	-	0.37	0.4	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	8	-	



plastic extremely thin small outline package; no leads; 8 terminals; 8 terminals; body 1.6 x 1.2 x 0.4 mm

2. Package outline

DFN1612-8: plastic extremely thin small outline package; no leads; 8 terminals; 8 terminals; body 1.6 x 1.2 x 0.4 mm

SOT1225

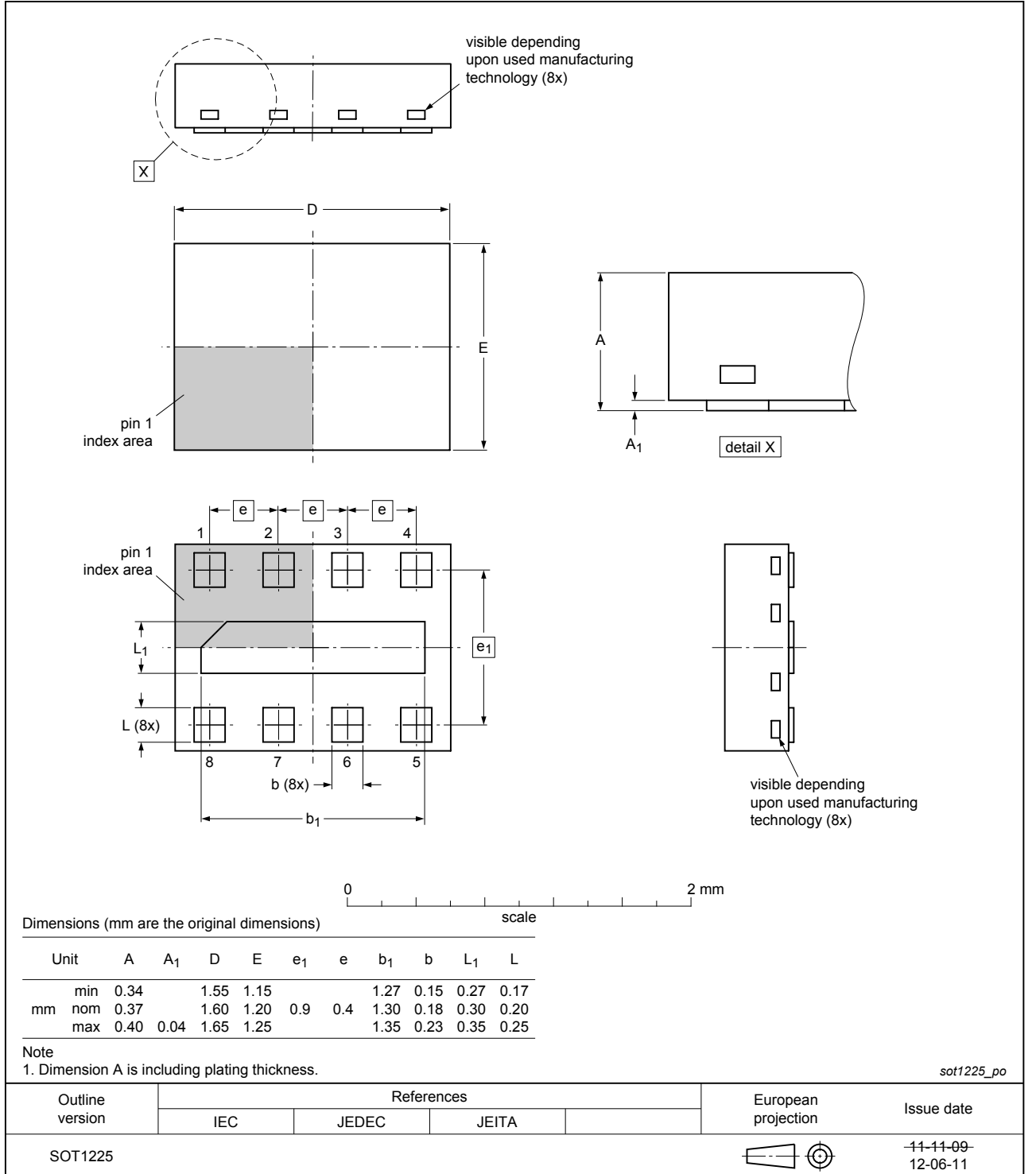


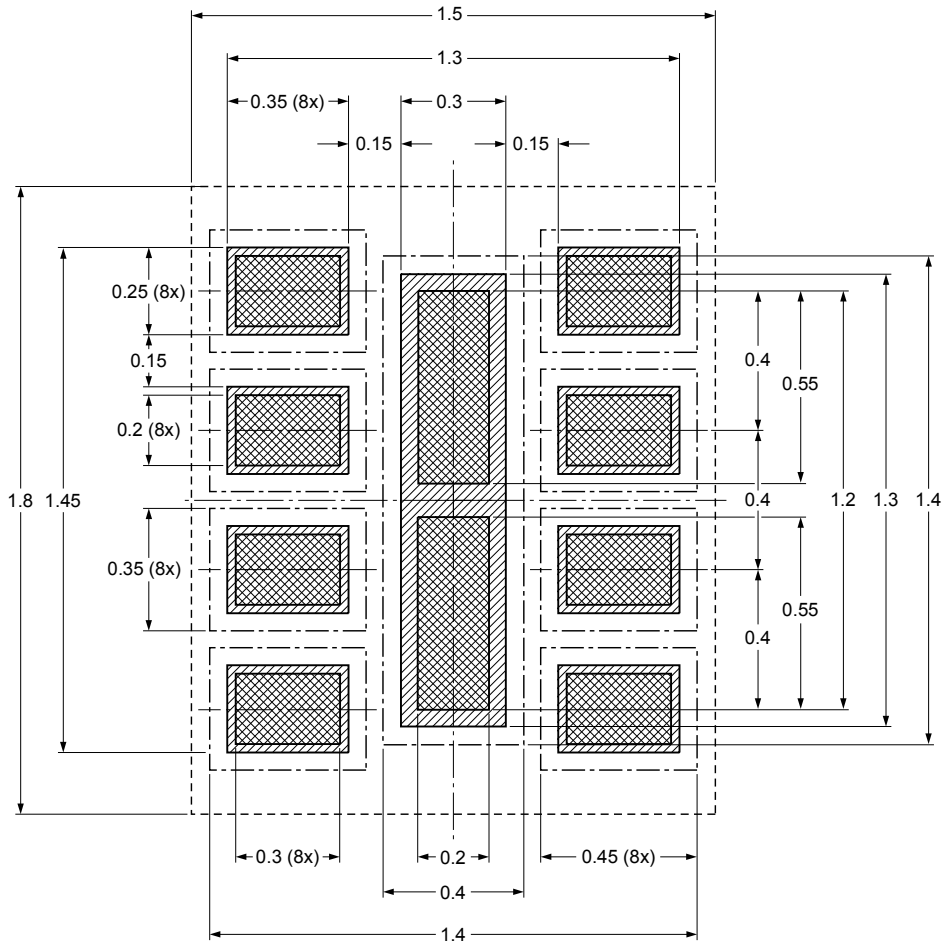
Fig. 1. Package outline DFN1612-8 (SOT1225)





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3. Soldering

Footprint information for reflow soldering of DFN1612-8 package

SOT1225



-  occupied area
-  solder land plus solder paste
-  solder lands
-  solder paste

12-10-12
13-04-22

Dimensions in mm

sot1225_fr

Fig. 2. Reflow soldering footprint for DFN1612-8 (SOT1225)

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4. Legal information

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